

**SCHEME OF TEACHING AND EXAMINATION
M.Tech in VLSI DESIGN AND EMBEDDED SYSTEMS**

I SEMESTER

Sl. No	Subject Code	Title	Teaching Hours /Week		Examination				Credit
			Theory	Practical/Field Work/Assignment	Duration	I.A. Marks	Theory/Practical Marks	Total Marks	
1	16ELD11	Advanced Engineering Mathematics	4	-	3	20	80	100	4
2	16EVE12	Digital VLSI Design	4	-	3	20	80	100	4
3	16EVE13	Advanced Embedded System	4	-	3	20	80	100	4
4	16EVE14	Low Power VLSI Design	4	-	3	20	80	100	4
5	16EXX15X	Elective-1	3	-	3	20	80	100	3
6	16EVEL16	VLSI and ES Lab -1		3	3	20	80	100	2
7	16EVE17	Seminar on advanced topics from refereed journals	-	3	-	100	-	100	1
TOTAL			19	6	18	220	480	700	22

Elective -1	
16 EVE151	Digital System Design Using Verilog
16 EVE152	Nanoelectronics
16 EVE153	ASIC Design
16 ELD154	Advanced Computer Architecture

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II SEMESTER

Sl. No	Subject Code	Title	Teaching Hours /Week		Examination				Credit
			Theory	Practical/Field Work/Assignment	Duration	I.A. Marks	Theory/Practical Marks	Total Marks	
1	16EVE21	Design of Analog and Mixed mode VLSI Circuits	4	-	3	20	80	100	4
2	16EVE22	VLSI Testing	4	-	3	20	80	100	4
3	16EVE23	Advances in VLSI Design	4	-	3	20	80	100	4
4	16EVE24	Real Time Operating System	4	-	3	20	80	100	4
5	16EXX25X	Elective –2	3	-	3	20	80	100	3
6	16EVEL26	VLSI and ES Lab -2		3	3	20	80	100	2
7	16EVE27	Seminar on Advanced topics from refereed journals	-	3	-	100	-	100	1
TOTAL			19	6	18	220	480	700	22

Elective -2	
16EVE251	System Verilog
16EVE252	VLSI Design for Signal processing
16ELD253	Micro Electro Mechanical Systems
16EVE254	SoC Design

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III SEMESTER: Internship

Sl. No	Subject Code	Title	Teaching Hours /Week		Examination			Credit	
			Theory	Practical/Field Work/Assignment	Duration	I.A. Marks	Theory/Practical Marks		Total Marks
1	16EVE31	Seminar / Presentation on Internship (After 8 weeks from the date of commencement)	-	-	-	25	-	25	20
2	16EVE32	Report on Internship	-	-	-	25	-	25	
3	16EVE33	Evaluation and Viva-Voce of Internship	-	-	-	-	50	50	
4	16EVE34	Evaluation of Project phase -1	-	-	-	50	-	50	1
TOTAL			-	-	-	100	50	150	21

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IV SEMESTER

Sl. No	Subject Code	Title	Teaching Hours /Week		Examination				Credit
			Theory	Practical/Field Work/Assignment	Duration	I.A. Marks	Theory/Practical Marks	Total Marks	
1	16ELD41	Synthesis and Optimization of Digital Circuits	4	-	3	20	80	100	4
2	16EXX42X	Elective-3	3	-	3	20	80	100	3
3	16EVE43	Evaluation of Project phase -2	-	-	-	50	-	50	3
4	16EVE44	Evaluation of Project and Viva-Voce	-	-	-	-	100+100	200	10
TOTAL			-	-	6	90	360	450	20

Elective -3	
16EVE421	CMOS RF Circuit Design
16ECS422	Advances in Image Processing
16EVE423	High Speed VLSI Design
16ELD424	Reconfigurable Computing

Note:

- 1. Project Phase-1:** 6-week duration shall be carried out between 2nd and 3rd Semester vacation. Candidates in consultation with the guide shall carry out literature survey/ visit industries to finalize the topic of Project.
- 2. Project Phase-2:** 16-week duration during 4th semester. Evaluation shall be done by the committee constituted comprising of HoD as Chairman, Guide and Senior faculty of the department.
- 3. Project Evaluation:** Evaluation shall be taken up at the end of 4th semester. Project work evaluation and Viva-Voce examination shall be conducted.
 - a. Internal Examiner shall carry out the evaluation for 100 marks.
 - b. External Examiner shall carry out the evaluation for 100 marks.
 - c. The average of marks allotted by the internal and external examiner shall be the final marks of the project evaluation.
 - d. Viva-Voce examination of Project work shall be conducted jointly by Internal and External examiner for 100 marks.

M.Tech-VLSI & ES-2016-FIRST SEMESTER SYLLABUS

ADVANCED ENGINEERING MATHEMATICS			
[As per Choice Based Credit System (CBCS) scheme]			
SEMESTER – I			
Subject Code	16ELD11	IA Marks	20
Number of Lecture Hours/Week	04	Exam Marks	80
Total Number of Lecture Hours	50 (10 Hours per Module)	Exam Hours	03
CREDITS – 04			
<p>Course objectives: This course will enable students to:</p> <ul style="list-style-type: none"> • Acquaint with principles of linear algebra, calculus of variations, probability theory and random process. • Apply the knowledge of linear algebra, calculus of variations, probability theory and random process in the applications of electronics and communication engineering sciences. 			
Modules			Revised Bloom's Taxonomy (RBT) Level
Module -1			
<p>Linear Algebra-I Introduction to vector spaces and sub-spaces, definitions, illustrative examples and simple problems. Linearly independent and dependent vectors-definition and problems. Basis vectors, dimension of a vector space. Linear transformations- definition, properties and problems. Rank-Nullity theorem(without proof). Matrix form of linear transformations-Illustrative examples.(Text 1 & Ref. 1)</p>			L1,L2
Module -2			
<p>Linear Algebra-II Computation of Eigen values and Eigen vectors of real symmetric matrices-Given's method. Orthogonal vectors and orthogonal bases. Gram-Schmidt orthogonalization process. QR decomposition, singular value decomposition, least square approximations.(Text 1 & Ref. 1)</p>			L1,L2
Module -3			
<p>Calculus of Variations Concept of functional-Eulers equation. functional dependent on first and higher order derivatives, functional on several dependent variables. Isoperimetric problems-variation problems with moving boundaries.(Text 2 & Ref. 2)</p>			L1,L2
Module -4			

<p>Probability Theory Review of basic probability theory. Definitions of random variables and probability distributions, probability mass and density functions, expectation, moments, central moments, characteristic functions, probability generating and moment generating functions-illustrations. Binomial, Poisson, Exponential, Gaussian and Rayleigh distributions-examples.(Text 3 & Ref. 3)</p>	<p>L1,L2</p>
<p>Module -5</p>	
<p>Joint probability distributions Definition and properties of CDF, PDF, PMF, conditional distributions. Expectation, covariance and correlation. Independent random variables. Statement of central limit theorem-Illustrative examples. Random process- Classification, stationary and ergodic random process. Auto correlation function-properties, Gaussian random process.(Text 3 & Ref. 3)</p>	<p>L1,L2</p>
<p>Course Outcomes: After studying this course, students will be able to:</p> <ul style="list-style-type: none"> • Understand vector spaces, basis, linear transformations and the process of obtaining matrix of linear transformations arising in magnification and rotation of images. • Apply the techniques of QR and singular value decomposition for data compression, least square approximation in solving inconsistent linear systems. • Utilize the concepts of functionals and their variations in the applications of communication systems, decision theory, synthesis and optimization of digital circuits. • Learn the idea of random variables (discrete/continuous) and probability distributions in analyzing the probability models arising in control systems and system communications. • Apply the idea of joint probability distributions and the role of parameter-dependent random variables in random process. 	
<p>Question paper pattern:</p> <ul style="list-style-type: none"> • The question paper will have 10 full questions carrying equal marks. • Each full question consists of 16 marks with a maximum of four sub questions. • There will be 2 full questions from each module covering all the topics of the module • The students will have to answer 5 full questions, selecting one full question from each module. 	

Text Books:

1. David C.Lay, Steven R.Lay and J.J.McDonald: Linear Algebra and its Applications, 5th Edition, Pearson Education Ltd., 2015.
2. E. Kreyszig, "Advanced Engineering Mathematics", 10th edition, Wiley, 2015.
3. Scott L.Miller, Donald G. Childers: "Probability and Random Process with application to Signal Processing", Elsevier Academic Press, 2nd Edition, 2013.

Reference books:

1. Richard Bronson: "Schaum's Outlines of Theory and Problems of Matrix Operations", McGraw-Hill, 1988.
2. Elsgolts, L.: "Differential Equations and Calculus of Variations", MIR Publications, 3rd Edition, 1977.
3. T.Veerarajan: "Probability, Statistics and Random Process", 3rd Edition, Tata McGraw Hill Co., 2008.

Web links:

1. <http://nptel.ac.in/courses.php?disciplineId=111>
2. [http://www.class-central.com/subject/math\(MOOCs\)](http://www.class-central.com/subject/math(MOOCs))
3. <http://ocw.mit.edu/courses/mathematics/>
4. www.wolfram.com

DIGITAL VLSI DESIGN			
[As per Choice Based Credit System (CBCS) scheme]			
SEMESTER -I			
Subject Code	16EVE12	IA Marks	20
Number	04	Exam Marks	80
Total Number of	50 (10 Hours per Module)	Exam Hours	03
CREDITS – 04			
Course objectives: This course will enable students to:			
<ul style="list-style-type: none"> • Explain VLSI Design Methodologies • Learn Static and Dynamic operation principles, analysis and design of inverter circuit. • Infer state of the art Semiconductors Memory circuits. • Outline the comprehensive coverage of Methodologies and Design practice that are used to reduce the Power Dissipation of large scale digital circuits. • Illustrate VLSI and ASIC design. 			
Modules			Revised Bloom's Taxonomy (RBT) Level
Module -1			
MOS Transistor: The Metal Oxide Semiconductor (MOS) Structure, The MOS System under External Bias, Structure and Operation of MOS Transistor, MOSFET Current-Voltage Characteristics, MOSFET Scaling and Small-Geometry Effects. MOS Inverters-Static Characteristics: Introduction, Resistive-Load Inverter, Inverters with n_Type MOSFET Load.			L1, L2
Module -2			
MOS Inverters-Static Characteristics: CMOS Inverter. MOS Inverters: Switching Characteristics and Interconnect Effects: Introduction, Delay-Time Definition, Calculation of Delay Times, Inverter Design with Delay Constraints, Estimation of Interconnect Parasitics, Calculation of Interconnect Delay, Switching Power Dissipation of CMOS Inverters.			L2, L3
Module -3			

<p>Semiconductor Memories: Introduction, Dynamic Random Access Memory (DRAM), Static Random Access Memory (SRAM), Nonvolatile Memory, Flash Memory, Ferroelectric Random Access Memory (FRAM).</p>	<p>L1, L2, L3</p>
<p>Module -4</p>	
<p>Dynamic Logic Circuits: Introduction, Basic Principles of Pass Transistor Circuits, Voltage Bootstrapping, Synchronous Dynamic Circuit Techniques, Dynamic CMOS Circuit Techniques, High Performance Dynamic CMOS Circuits.</p> <p>BiCMOS Logic Circuits: Introduction, Bipolar Junction Transistor (BJT): Structure and Operation, Dynamic Behavior of BJTs, Basic BiCMOS Circuits: Static Behavior, Switching Delay in BiCMOS Logic Circuits, BiCMOS Applications.</p>	<p>L1,L2, L3</p>
<p>Module -5</p>	
<p>Chip Input and Output (I/O) Circuits: Introduction, ESD Protection, Input Circuits, Output Circuits and L(di/dt) Noise, On-Chip Clock Generation and Distribution, Latch-Up and Its Prevention.</p> <p>Design for Manufacturability: Introduction, Process Variations, Basic Concepts and Definitions, Design of Experiments and Performance Modeling.</p>	<p>L2, L3</p>
<p>Course outcomes: After studying this course, students will be able to:</p> <ol style="list-style-type: none"> 1. Analyse issues of On-chip interconnect Modelling and Interconnect delay calculation. 2. Analyse the Switching Characteristics in Digital Integrated Circuits. 3. Use the Dynamic Logic circuits in state-of-the-art VLSI chips. 4. Study critical issues such as ESD protection, Clock distribution, Clock buffering, and Latch phenomenon 5. Use Bipolar and Bi-CMOS circuits in very high speed design. 	
<p>Question Paper Pattern</p> <ul style="list-style-type: none"> · The question paper will have 10 full questions carrying equal marks. · Each full question consists of 16 marks with a maximum of four sub questions. · There will be 2 full questions from each module covering all the topics of the module · The students will have to answer 5 full questions, selecting one full question from each module. 	
<p>Text Book: Sung Mo Kang & Yosuf Leblebici, “CMOS Digital Integrated Circuits: Analysis and Design”, Tata McGraw-Hill, Third Edition.</p>	

Reference Books:

1. Neil Weste and K. Eshragian, "Principles of CMOS VLSI Design: A System Perspective", Second Edition, Pearson Education (Asia) Pvt. Ltd. 2000.
2. Wayne, Wolf, "Modern VLSI Design: System on Silicon" Prentice Hall PTR/Pearson Education, Second Edition, 1998.
3. Douglas A Pucknell & Kamran Eshragian, "Basic VLSI Design" PHI 3rd Edition (original Edition – 1994).

ADVANCED EMBEDDED SYSTEM

[As per Choice Based Credit System (CBCS) scheme]

SEMESTER – I

Subject Code	16EVE13	IA Marks	20
Number of Lecture Hours/Week	04	Exam Marks	80
Total Number of Lecture Hours	50 (10 Hours per Module)	Exam Hours	03

CREDITS – 04

Course objectives: This course will enable students to:

- Understand the basic hardware components and their selection method based on the characteristics and attributes of an embedded system.
- Describe the hardware software co-design and firmware design approaches
- Explain the architectural features of ARM CORTEX M3, a 32 bit microcontroller including memory map, interrupts and exceptions.
- Program ARM CORTEX M3 using the various instructions, for different applications.

Modules**Revised Bloom's Taxonomy (RBT) Level****Module -1**

Embedded System: Embedded vs General computing system, classification, application and purpose of ES. Core of an Embedded System, Memory, Sensors, Actuators, LED, Opto coupler, Communication Interface, Reset circuits, RTC, WDT, Characteristics and Quality Attributes of Embedded Systems (Text 1: Selected Topics from Ch -1, 2, 3).

L1, L2, L3**Module -2**

Hardware Software Co-Design, embedded firmware design approaches, computational models, embedded firmware development languages, Integration and testing of Embedded Hardware and firmware, Components in embedded system development environment (IDE), Files generated during compilation, simulators, emulators and debugging (Text 1: Selected Topics From Ch-7, 9, 12, 13).

L1, L2, L3

Module -3	
ARM-32 bit Microcontroller: Thumb-2 technology and applications of ARM, Architecture of ARM Cortex M3, Various Units in the architecture, General Purpose Registers, Special Registers, exceptions, interrupts, stack operation, reset sequence (Text 2: Ch 1, 2, 3)	L1, L2, L3
Module -4	
Instruction Sets: Assembly basics, Instruction list and description, useful instructions, Memory Systems, Memory maps, Cortex M3 implementation overview, pipeline and bus interface (Text 2: Ch-4, 5, 6)	L1, L2, L3
Module -5	
Exceptions, Nested Vector interrupt controller design, SysTick Timer, Cortex-M3 Programming using assembly and C language, CMSIS (Text 2: Ch-7, 8, 10)	L1, L2, L3
<p>Course Outcomes: After studying this course, students will be able to:</p> <ul style="list-style-type: none"> ● Understand the basic hardware components and their selection method based on the characteristics and attributes of an embedded system. ● Explain the hardware software co-design and firmware design approaches. ● Acquire the knowledge of the architectural features of ARM CORTEX M3, a 32 bit microcontroller including memory map, interrupts and exceptions. ● Apply the knowledge gained for Programming ARM CORTEX M3 for different applications. 	
<p>Question paper pattern:</p> <ul style="list-style-type: none"> · The question paper will have 10 full questions carrying equal marks. · Each full question consists of 16 marks with a maximum of four sub questions. · There will be 2 full questions from each module covering all the topics of the module · The students will have to answer 5 full questions, selecting one full question from each module. 	
<p>Text Books:</p> <ol style="list-style-type: none"> 1. K. V. Shibu, "Introduction to embedded systems", TMH education Pvt. Ltd. 2009. 2. Joseph Yiu, "The Definitive Guide to the ARM Cortex-M3", 2ndedn, Newnes, (Elsevier), 2010. 	
<p>Reference Book:</p> <p>James K. Peckol, "Embedded systems- A contemporary design tool", John Wiley, 2008.</p>	

LOW POWER VLSI DESIGN

[As per Choice Based Credit System (CBCS) scheme]

SEMESTER –I

Subject Code	16EVE14	IA Marks	20
Number of Lecture	04	Exam Marks	80
Total Number of Lecture Hours	50 (10 Hours per Module)	Exam Hours	03

CREDITS – 04

Course objectives: This course will enable students to:

- Know the basics and advanced techniques in low power design which is a hot topic in today's market where the power plays a major role.
- Describe the various power reduction and the power estimation methods.
- Explain power dissipation at all layers of design hierarchy from technology, circuit, logic, architecture and system
- Apply State-of-the art approaches to power estimation and reduction.
- Practice the low power techniques using current generation design style and process technology

Modules**Revised Bloom's Taxonom****Module -1**

Introduction: Need for low power VLSI chips, charging and discharging capacitance, short circuit current in CMOS leakage current, static current, basic principles of low power design, low power figure of merits.

Simulation power analysis: SPICE circuit simulation, discrete transistor modeling and analysis, gate level logic simulation, architecture level analysis, data correlation analysis in DSP systems, Monte Carlo simulation. (Text 1)

L1, L2**Module -2**

Probabilistic power analysis: Random logic signals, probability & frequency, probabilistic power analysis techniques, signal entropy.

Circuit: Transistor and gate sizing, equivalent pin ordering, network restructuring and reorganization, special latches and flip flops, low power digital cell library, adjustable device threshold voltage. (Text 1)

L1, L2, L3**Module -3**

Logic: Gate reorganization, signal gating, logic encoding, state machine encoding, pre-computation logic (Text 1).

Low power Clock Distribution: Power dissipation in clock distribution, single driver Vs distributed buffers, Zero skew Vs tolerable skew, chip & package co design of clock network (Text 2).

L1, L2, L3**Module -4**

<p>Low power Architecture & Systems: Power & performance management, switching activity reduction, parallel architecture with voltage reduction, flow graph transformation (Text 1).</p> <p>Low power arithmetic components: Introduction, circuit design style, adders, multipliers, division (Text 2).</p>	L1- L4
Module -5	
<p>Low power memory design: Introduction, sources and reductions of power dissipation in memory subsystem, sources of power dissipation in DRAM and SRAM (Text 2).</p> <p>Algorithm & Architectural Level Methodologies: Introduction, design flow, Algorithmic level analysis & optimization, Architectural level estimation & synthesis (Text 2).</p> <p>Advanced Techniques: Adiabatic computation, pass transistor, Asynchronous circuits (Text 1).</p>	L1-L4
<p>Course outcomes: After studying this course, students will be able to:</p> <ul style="list-style-type: none"> • Identify the sources of power dissipation in CMOS circuits. • Perform power analysis using simulation based approaches and probabilistic analysis. • Use optimization and trade-off techniques that involve power dissipation of digital circuits. • Make the power design a reality by making power dimension an integral part of the design process • Use practical low power design techniques and their analysis at various levels of design abstraction and analyse how these are being captured in the latest design automation environments. 	
<p>Question paper pattern:</p> <ul style="list-style-type: none"> • The question paper will have 10 full questions carrying equal marks. • Each full question consists of 16 marks with a maximum of four sub questions. • There will be 2 full questions from each module covering all the topics of the module • The students will have to answer 5 full questions, selecting one full question from each module. 	
<p>Text Books:</p> <ol style="list-style-type: none"> 1. Gary K. Yeap, “Practical Low Power Digital VLSI Design”, Kluwer Academic, 1998. 2. Jan M.Rabaey, Massoud Pedram, “Low Power Design Methodologies”, Kluwer Academic, 2010. 	
<p>Reference Books:</p> <ol style="list-style-type: none"> 1. Kaushik Roy, Sharat Prasad, “Low-Power CMOS VLSI Circuit Design” Wiley, 2000 2. A.P.Chandrasekaran and R.W.Brodersen, “Low power digital CMOS design”, Kluwer Academic,1995. 3. A Bellamour and M I Elmasri, “ Low power VLSI CMOS circuit design”, Kluwer Academic,1995. 	

DIGITAL SYSTEM DESIGN USING VERILOG

[As per Choice Based Credit System (CBCS) scheme]

SEMESTER – I

Subject Code	16EVE151	IA Marks	20
Number of Lecture Hours/Week	03	Exam Marks	80
Total Number of Lecture Hours	40 (08 Hours per Module)	Exam Hours	03

CREDITS – 03

Course objectives: This course will enable students to:

- Understand the concepts of Verilog Language
- Design the digital systems as an activity in a larger systems design context.
- Study the design and operation of semiconductor memories frequently used in application specific digital system.
- Inspect how effectively IC's are embedded in package and assembled in PCB's for different application
- Design and diagnosis of processors and I/O controllers they can be used in embedded systems

Modules

Revised Bloom's Taxonomy (RBT)

Module -1

Introduction and Methodology: Digital Systems and Embedded Systems, Binary representation and Circuit Elements, Real-World Circuits, Models, Design Methodology.

L1, L2

Module -2

Number Basics: Unsigned and Signed Integers, Fixed and Floating-point Numbers.
Sequential Basics: Storage elements, Counters, Sequential Data paths and Control, Clocked Synchronous Timing Methodology.

L1, L2

Module -3

Memories: Concepts, Memory Types, Error Detection and Correction.
Implementation Fabrics: ICs, PLDs, Packaging and Circuit Boards, Interconnection and Signal Integrity.

L1, L2

Module -4

Processor Basics: Embedded Computer Organization, Instruction and Data, Interfacing with memory.
I/O interfacing: I/O devices, I/O controllers, Parallel Buses, Serial Transmission, I/O software.

L2, L3

Module -5

<p>Accelerators: Concepts, case study, Verification of accelerators. Design Methodology: Design flow, Design optimization, Design for test.</p>	<p>L2, L3</p>
<p>Course Outcomes: After studying this course, students will be able to:</p> <ul style="list-style-type: none"> • Design embedded systems, using small microcontrollers, larger CPUs/DSPs, or hard or soft processor cores. • Design the combinational circuits using discrete gates and programmable logic devices. • Describe Verilog model for sequential circuits and test pattern generation • Explore the different types of semiconductor memories and their usage for specific chip design • Synthesis different types of processor and I/O controllers that are used in embedded system design 	
<p>Question paper pattern:</p> <ul style="list-style-type: none"> · The question paper will have 10 full questions carrying equal marks. · Each full question consists of 16 marks with a maximum of four sub questions. · There will be 2 full questions from each module covering all the topics of the module · The students will have to answer 5 full questions, selecting one full question from each module. 	
<p>Text Book: Peter J. Ashenden, “Digital Design: An Embedded Systems Approach Using VERILOG”, Elsevier, 2010.</p>	
<p>Reference Book: Verilog HDL: A Guide to Digital Design and Synthesis, Second Edition by Samir Palnitkar.</p>	

NANOELECTRONICS

[As per Choice Based Credit System (CBCS) scheme]

Subject Code	16EVE152	IA Marks	20
Number of Lecture Hours/Week	03	Exam Marks	80
Total Number of Lecture Hours	40 (08 Hours per Module)	Exam Hours	03

CREDITS – 03

Course objectives: This course will enable students to:

- Enhance basic engineering science and technological knowledge of nanoelectronics.
- Explain basics of top-down and bottom-up fabrication process, devices and systems.
- Describe technologies involved in modern day electronic devices.
- Appreciate the complexities in scaling down the electronic devices in the future.

Modules	Revised Bloom's Taxonomy (RBT) Level
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Module -1

Introduction: Overview of nanoscience and engineering. Development milestones in microfabrication and electronic industry. Moores' law and continued miniaturization, Classification of Nanostructures, Electronic properties of atoms and solids: Isolated atom, Bonding between atoms, Giant molecular solids, Free electron models and energy bands, crystalline solids, Periodicity of crystal lattices, Electronic conduction, effects of nanometer length scale, Fabrication methods: Top down processes, Bottom up processes methods for templating the growth of nanomaterials, ordering of nanosystems (Text 1).

L1, L2**Module -2**

Characterization: Classification, Microscopic techniques, Field ion microscopy, scanning probe techniques, diffraction techniques: bulk and surface diffraction techniques (Text1).

L1,L2,L3**Module -3**

<p>Characterization: spectroscopy techniques: photon, radiofrequency, electron, surface analysis and dept profiling: electron, mass, Ion beam, Reflectometry, Techniques for property measurement: mechanical, electron, magnetic, thermal properties.</p> <p>Inorganic semiconductor nanostructures: overview of semiconductor physics. Quantum confinement in semiconductor nanostructures: quantum wells, quantum wires, quantum dots, super-lattices, band offsets, electronic density of states (Text1).</p>	L1-L3
Module -4	
<p>Fabrication techniques: requirements of ideal semiconductor, epitaxial growth of quantum wells, lithography and etching, cleaved-edge over growth, growth of vicinal substrates, strain induced dots and wires, electrostatically induced dots and wires, Quantum well width fluctuations, thermally annealed quantum wells, semiconductor nanocrystals, collidal quantum dots, self-assembly techniques.</p> <p>Physical processes: modulation doping, quantum hall effect, resonant tunneling, charging effects, ballistic carrier transport, Inter band absorption, intra band absorption, Light emission processes, phonon bottleneck, quantum confined stark effect, nonlinear effects, coherence and dephasing, characterization of semiconductor nanostructures: optical electrical and structural (Text1).</p>	L1-L3
Module -5	
<p>Methods of measuring properties: atomic, crystallography, microscopy, spectroscopy (Text 2).</p> <p>Applications: Injection lasers, quantum cascade lasers, single-photon sources, biological tagging, optical memories, coulomb blockade devices, photonic structures, QWIP's, NEMS, MEMS (Text 1).</p>	L1-L3
<p>Course outcomes: After studying this course, students will be able to:</p> <ul style="list-style-type: none"> • Know the principles behind Nanoscience engineering and Nanoelectronics. • Apply the knowledge to prepare and characterize nanomaterials. • Know the effect of particles size on mechanical, thermal, optical and electrical properties of nanomaterials. • Design the process flow required to fabricate state of the art transistor technology. • Analyze the requirements for new materials and device structure in the future technologies. 	
<p>Question paper pattern:</p> <ul style="list-style-type: none"> • The question paper will have 10 full questions carrying equal marks. • Each full question consists of 16 marks with a maximum of four sub questions. • There will be 2 full questions from each module covering all the topics of the module • The students will have to answer 5 full questions, selecting one full question from each module. 	

Text Books:

1. Ed Robert Kelsall, Ian Hamley, Mark Geoghegan, "Nanoscale Science and Technology", John Wiley, 2007.
2. Charles P Poole, Jr, Frank J Owens, "Introduction to Nanotechnology", John Wiley, Copyright 2006, Reprint 2011.

Reference Book:

Ed William A Goddard III, Donald W Brenner, Sergey E. Lyshevski, Gerald J Iafrate, "Hand Book of Nanoscience Engineering and Technology", CRC press, 2003.

ASIC DESIGN

[As per Choice Based Credit System (CBCS) scheme]
SEMESTER – I

Subject Code	16EVE153	IA Marks	20
Number of Lecture Hours/Week	03	Exam Marks	80
Total Number of Lecture Hours	40	Exam Hours	03

CREDITS – 03

Course objectives: This course will enable students to:

- Explain ASIC methodologies and programmable logic cells to implement a function on IC.
- Analyse back-end physical design flow, including partitioning, floor-planning, placement, and routing.
- Gain sufficient theoretical knowledge for carrying out FPGA and ASIC designs.
- Design CAD algorithms and explain how these concepts interact in ASIC design.

Modules

**Revised
Bloom's
Taxonomy
(RBT)Level**

Module -1

Introduction to ASICs, Full custom, Semi-custom and Programmable ASICs, ASIC Design flow, ASIC cell libraries.

CMOS Logic: Datapath Logic Cells: Data Path Elements, Adders: Carry skip, Carry bypass, Carry save, Carry select, Conditional sum, Multiplier (Booth encoding), Data path Operators, I/O cells.

L1,L2

Module -2

ASIC Library Design: Logical effort: Predicting Delay, Logical area and logical efficiency, Logical paths, Multi stage cells, Optimum delay and number of stages.

Programmable ASIC Logic Cells:

MUX as Boolean function generators, Actel ACT: ACT 1, ACT 2 and ACT 3 Logic Modules, Xilinx LCA: XC3000 CLB, Altera FLEX and MAX.

L1-L3

Module -3

Programmable ASIC I/O Cells: Xilinx and Altera I/O Block.

Low-level design entry: Schematic entry: Hierarchical design, Netlist screener.

ASIC Construction: Physical Design, CAD Tools.

Partitioning: Goals and objectives, Constructive Partitioning, Iterative Partitioning Improvement, KL, FM and Look Ahead algorithms.

L1-L4

Module -4

Floor planning and placement: Goals and objectives, Floor planning tools, Channel definition, I/O and Power planning and Clock planning.

Placement: Goals and Objectives, Min-cut Placement algorithm, Iterative Placement Improvement, Physical Design Flow.

L1-L3

Module -5	
Routing: Global Routing: Goals and objectives, Global Routing Methods, Back-annotation. Detailed Routing: Goals and objectives, Measurement of Channel Density, Left-Edge and Area-Routing Algorithms. Special Routing, Circuit extraction and DRC.	L1-L3
<p>Course outcomes: After studying this course, students will be able to:</p> <ul style="list-style-type: none"> • Describe the concepts of ASIC design methodology, data path elements, logical effort and FPGA architectures. • Analyze the design of FPGAs and ASICs suitable for specific tasks, perform design entry and explain the physical design flow. • Design data path elements for ASIC cell libraries and compute optimum path delay. • Create floor plan including partition and routing with the use of CAD algorithms. 	
<p>Question paper pattern:</p> <ul style="list-style-type: none"> • The question paper will have 10 full questions carrying equal marks. • Each full question consists of 16 marks with a maximum of four sub questions. • There will be 2 full questions from each module covering all the topics of the module • The students will have to answer 5 full questions, selecting one full question from each module. 	
<p>Text Book: Michael John Sebastian Smith, “Application - Specific Integrated Circuits” Addison-Wesley Professional; 2005.</p>	
<p>Reference Books:</p> <ol style="list-style-type: none"> 1. Neil H.E. Weste, David Harris, and Ayan Banerjee, “CMOS VLSI Design: A Circuits and Systems Perspective”, 3rd edition, Addison Wesley/ Pearson education, 2011. 2. Vikram Arkalgud Chandrasetty, “VLSI Design: A Practical Guide for FPGA and ASIC Implementations”, Springer, 2011, ISBN: 978-1-4614-1119-2. 3. Rakesh Chadha, Bhasker J., “An ASIC Low Power Primer”, Springer, ISBN: 978-1-4614-4270-7. 	

ADVANCED COMPUTER ARCHITECTURE			
[As per Choice Based Credit System (CBCS) scheme]			
SEMESTER – I			
Subject Code	16ELD154	IA Marks	20
Number of Lecture Hours/Week	03	Exam Marks	80
Total Number of Lecture Hours	40	Exam Hours	03
CREDITS – 03			
<p>Course objectives: This course will enable students to:</p> <ul style="list-style-type: none"> • Understand the basic concepts for parallel processing • Analyze program partitioning and flow mechanisms • Apply pipelining concept for the performance evaluation • Learn the advanced processor architectures for suitable applications 			
Modules			Revised Bloom's Taxonomy (RBT) Level
Module -1			
<p>Parallel Computer Models: Classification of parallel computers, Multiprocessors and multicomputers, Multivector and SIMD computers. Program and Network Properties, Conditions of parallelism, Data and resource Dependences, Hardware and software parallelism. (Text 1)</p>			L2, L3, L4
Module -2			
<p>Program partitioning and scheduling, Grain Size and latency, Program flow mechanisms, Control flow versus data flow, Data flow Architecture, Demand driven mechanisms, Comparisons of flow mechanisms, Principles of Scalable Performance, Performance Metrics and Measures, Parallel Processing Applications, Speedup Performance Laws, Scalability Analysis and Approaches. (Text 1)</p>			L2, L3, L4
Module -3			
<p>Advanced Processors: Advanced processor technology, Instruction-set Architectures, CISC Scalar Processors, RISC Scalar Processors, Superscalar Processors, VLIW Architectures, Pipelining, Linear pipeline processor, nonlinear pipeline processor, Instruction pipeline design. (Text 1)</p>			L1, L2, L3
Module -4			
<p>Mechanisms for instruction pipelining, Dynamic instruction scheduling, Branch Handling techniques, branch prediction, Arithmetic Pipeline Design, Computer arithmetic principles, Static Arithmetic pipeline, Multifunctional arithmetic pipelines. (Text 1)</p>			L2, L3, L4
Module -5			

<p>Multithread and Dataflow Architecture: Principles of Multithreading, Scalable and Multithreaded Architecture, Dataflow Architecture, Symmetric shared memory architecture, distributed shared memory architecture. (Text 1 & 2)</p>	<p>L1, L2, L3</p>
<p>Course outcomes: At the end of this course, the students will be able to:</p> <ul style="list-style-type: none"> • Understand the basic concepts for parallel processing • Analyze program partitioning and flow mechanisms • Apply pipelining concept for the performance evaluation • Learn the advanced processor architectures for suitable applications 	
<p>Question paper pattern:</p> <ul style="list-style-type: none"> · The question paper will have 10 full questions carrying equal marks. · Each full question consists of 16 marks with a maximum of four sub questions. · There will be 2 full questions from each module covering all the topics of the module · The students will have to answer 5 full questions, selecting one full question from each module. 	
<p>Text Books:</p> <ol style="list-style-type: none"> 1. Kai Hwang, “Advanced computer architecture”, TMH. 2007. 2. Kai Hwang and Zu, “Scalable Parallel Computers Architecture”, MGH, 2008. 	
<p>Reference Books:</p> <ol style="list-style-type: none"> 1. M.J. Flynn, “Computer Architecture, Pipelined and Parallel Processor Design”, Narosa Publishing, 2002. 2. D.A.Patterson, J.L.Hennessy, “Computer Architecture: A quantitative approach”, Morgan Kauffmann feb,2002. 	

VLSI and ES LAB - 1

[As per Choice Based Credit System (CBCS) scheme]

SEMESTER – I

Laboratory Code	16EVEL16	IA Marks	20
Number of Lecture Hours/Week	01Hr Tutorial (Instructions) + 02 Hours Laboratory	Exam Marks	80
		Exam Hours	03

CREDITS – 02

Course objectives: This course will enable students to:

- Learn Verilog Code Programming for the design of digital circuits
- Use FPGA/CPLD board and Logic Analyzer or Chipscope to verify the results
- Learn Assembly language programming for different applications using ARM-Cortex M3 Kit and Keil uVision- 4 tool.
- Learn C language programming for different applications using ARM- Cortex M3 Kit and Keil uVision-4 tool.

Laboratory Experiments:	Revised Bloom's Taxonomy
<p>1) Digital Design Experiments: Using Verilog code and any Compiler. Download code to FPGA/CPLD board and verify the output using Logic Analyzer or Chipscope</p> <ul style="list-style-type: none">a) Design and verify an 8 to 3 programmable priority encoderb) Design and verify 3-bit Arbitrary Counter and repeat the given sequencec) Design and Verify BCD adder and subtractord) Design and verify a sequential block to generate a sequence (say 11101) using appropriate FSM.e) Design and verify 8 bit Ripple carry adder and Carry skip adder.f) Design and verify a Linear feedback shift register based on a given polynomial expressiong) Design and verify the following 8 bit multipliers. Also report on area delay trade-off<ul style="list-style-type: none">i) Serial Multiplierii) Parallel Multiplierh) Design and verify a parameterized FIFOi) Design and verify register file which has 32-entry 3-ports having explicit address decoder. The ports are dedicated for read and write and will take one clock cycle for read or write operation	L2,L3,L4

<p>2) ARM Cortex M3 Programs: (Programming to be done using Keil uVision 4 and download the program on to a M3 evaluation board such as NXP LPC1768 or ATMEL ATSAM3U)</p> <ol style="list-style-type: none"> a) Write an Assembly language program to calculate the sum and display the result for the addition of first ten numbers. SUM = 10+9+8+.....+1 b) Write a Assembly language program to link multiple object files and link them together c) Write an Assembly language program to store data in RAM d) Write a C program to Output the “Hello World” message using UART e) Write a C program to Design a Stopwatch using interrupts 	<p>L2,L3,L4</p>
<p>Course outcomes: On the completion of this laboratory course, the students will be able to:</p> <ul style="list-style-type: none"> • Develop Verilog Code for the design of digital circuits • Use FPGA/CPLD board and Logic Analyzer or Chipscope to verify the results • Develop Assembly language programs for different applications using ARM-Cortex M3 Kit and Keil uVision-4 tool. • Develop C language programs for different applications using ARM-Cortex M3 Kit and Keil uVision-4 tool 	
<p>Conduct of Practical Examination:</p> <ul style="list-style-type: none"> • All laboratory experiments are to be included for practical examination. • For examination, two questions using different tool to be set. • Students are allowed to pick one experiment from the lot. • Strictly follow the instructions as printed on the cover page of answer script for breakup of marks. • Change of experiment is allowed only once and Marks allotted to the procedure part to be made zero. 	

M.Tech-VLSI & ES-2016-SECOND SEMESTER SYLLABUS

Design of Analog and Mixed Mode VLSI Circuits [As per Choice Based credit System (CBCS) Scheme SEMESTER – II			
Subject Code	16EVE21	IA Marks	20
Number of Lecture Hours/Week	04	Exam marks	80
Total Number of Lecture Hours	50 (10 Hours per Module)	Exam Hours	03
CREDITS – 04			
<p>Course Objectives: This course will enable students to:</p> <ul style="list-style-type: none"> ● Describe basic physics and operation of MOS devices. ● Exemplify single-stage and differential amplifiers and current mirrors ● Describe operational amplifiers ● Learn the design of phase-locked-loops ● Know the role of Data converters in an ever-increasing digital world. 			
Modules			RBT Level
Module 1			
Basic MOS Device Physics: General considerations, MOS I/V Characteristics, second order effects, MOS device models.			L1, L2
Single stage Amplifier: Basic Concepts, Common Source stage.(Text 1)			
Module 2			
Single stage Amplifier: Source follower, common-gate stage, Cascode Stage, choice of device models.			L1,L2
Differential Amplifiers: Single ended and differential operation, Basic differential pair, Common mode response, Differential pair with MOS loads, Gilbert cell. (Text 1)			
Module 3			
Passive and Active Current Mirrors: Basic current mirrors, Cascode Current mirrors, Active Current mirrors.			L1,L2,L3
Operational Amplifiers (part-1): General Considerations, One Stage OP-Amp, Two Stage OP-Amp, Gain boosting. (Text 1)			
Module 4			
Operational Amplifiers (part-2): Common Mode Feedback, Slew rate, Power Supply Rejection.			L1,L2,L3
Phase Locked Loops: Simple PLL, Charge pump PLLs, Non-ideal effects in PLLs, Delay-Locked Loops, Applications. (Text 1)			
Module 5			
Data Converter Architectures: DAC & ADC Specifications, Current Steering DAC, Charge Scaling DAC, Cyclic DAC, Pipeline DAC, Flash ADC, Pipeline ADC, Integrating ADC, Successive Approximation ADC. (Text 2)			L1,L2,L3

Course Outcomes: After studying this course, students will be able to:

- Use efficient analytical tools for quantifying the behaviour of basic circuits by inspection.
- Design high-performance, stable operational amplifiers with the trade-offs between speed, precision and power dissipation.
- Design and study the behaviour of phase-locked-loops for the applications.
- Identify the critical parameters that affect the analog and mixed-signal VLSI circuits' performance
- Perform calculations in the digital or discrete time domain, more sophisticated data converters to translate the digital data to and from inherently analog world.

Question paper pattern:

- The question paper will have 10 full questions carrying equal marks.
- Each full question consists of 16 marks with a maximum of four sub questions.
- There will be 2 full questions from each module covering all the topics of the module
- The students will have to answer 5 full questions, selecting one full question from each module.

Text Books:

1. Behzad Razavi, "Design of Analog CMOS Integrated Circuits", TMH, 2007.
2. R. Jacob Baker, "CMOS Circuit Design, Layout, and Simulation", Second Edition, Wiley.

Reference Book:

Phillip E. Allen, Douglas R. Holberg, "CMOS Analog Circuit Design", Second Edition, Oxford University Press.

VLSI Testing			
[As per Choice Based credit System (CBCS) Scheme SEMESTER – II			
Subject Code	16EVE22	IA Marks	20
Number of Lecture Hours/Week	04	Exam marks	80
Total Number of Lecture Hours	50 (10 Hours per Module)	Exam Hours	03
CREDITS – 04			
<p>Course Objectives: This course will enable students to:</p> <ul style="list-style-type: none"> • Learn various types of faults and fault modeling • Comprehend the need for testing and testable design of digital circuits • Illustrate methods and algorithms for testing digital combinatorial networks and test pattern generation • Exemplify methods for testing sequential circuits and memory testing • Inferring testing methods using Boundary scan, Built-in self test and other advanced topics in digital circuit design. 			
Modules			RBT Level
Module 1			
<p>Faults in digital circuits: Failures and Faults, Modeling of faults, Temporary Faults. (Text 1)</p> <p>Logic Simulation: Applications, Problems in simulation based design verification, types of simulation, The unknown logic values, compiled simulation, event-driven simulation, Delay models, Element evaluation, Hazard detection, Gate-level event-driven Simulation. (Text 2)</p>			L1,L2
Module 2			
<p>Test generation for Combinational Logic circuits: Fault Diagnosis of digital circuits, Test generation techniques for combinational circuits, Detection of multiple faults in Combinational logic circuits. (Text 1)</p> <p>Testable Combinational logic circuit design: The Read-Muller expansion technique, Three level OR-AND-OR design, Automatic synthesis of testable logic.(Text 1)</p>			L1,L2,L3
Module 3			
<p>Testable Combinational logic circuit design: Testable design of multilevel combinational circuits, Synthesis of random pattern testable combinational circuits, Path delay fault testable combinational logic design, Testable PLA design. (Text 1)</p> <p>Test generation for Sequential circuits: Testing of sequential circuits as Iterative combinational circuits, state table verification, Test generation based on Circuit Structure, Functional Fault models, test Generation based on Functional Fault models. (Text 1)</p>			L1,L2,L3
Module 4			
<p>Design of testable sequential circuits: Controllability and observability, Ad-Hoc design rules for improving testability, design of</p>			L1,L2,L3

<p>diagnosable sequential circuits, the scan-path technique for testable sequential circuit design, Level Sensitive Scan Design(LSSD), Random Access Scan Technique, Partial scan, testable sequential circuit design using Nonscan Techniques, Cross check, Boundary Scan. (Text 1)</p>	
<p>Module 5</p>	
<p>Built-In Self Test: Test pattern generation for BIST, Output response analysis, Circular BIST, BIST Architectures. (Text 1)</p> <p>Testable Memory Design: RAM Fault Models, Test algorithms for RAMs, Detection of pattern-sensitive faults, BIST techniques for RAM chips, Test generation and BIST for embedded RAMs. (Text1)</p>	L1,L2,L3
<p>Course Outcomes: After studying this course, students will be able to:</p> <ul style="list-style-type: none"> • Analyze the need for fault modeling and testing of digital circuits • Generate fault lists for digital circuits and compress the tests for efficiency • Create tests for digital memories and analyze failures in them • Apply boundary scan technique to validate the performance of digital circuits • Design built-in self tests for complex digital circuits 	
<p>Question paper pattern:</p> <ul style="list-style-type: none"> • The question paper will have 10 questions carrying equal marks. • Each full question consists of 16 marks with a maximum of four sub questions. • There will be 2 full questions from each module covering all the topics of the module • The students will have to answer 5 full questions, selecting one full question from each module. 	
<p>Text Books:</p> <ol style="list-style-type: none"> 1. Lala Parag K., Digital Circuit Testing and Testability, New York, Academic Press, 1997. 2. Abramovici M, Breuer M A and Friedman A D, “Digital Systems Testing and Testable Design”, Wiley, 1994. 	
<p>Reference Books:</p> <ol style="list-style-type: none"> 1. Vishwani D Agarwal, “Essential of Electronic Testing for Digital, Memory and Mixed Signal Circuits”, Springer, 2002. 2. Wang, Wu and Wen, “VLSI Test Principles and Architectures”, Morgan Kaufmann, 2006. 	

Advances in VLSI Design			
[As per Choice Based credit System (CBCS) Scheme SEMESTER – II			
Subject Code	16EVE23	IA Marks	20
Number of Lecture Hours/Week	04	Exam marks	80
Total Number of Lecture Hours	50 (10 Hours per Module)	Exam Hours	03
CREDITS – 04			
Course Objectives: This course will enable the students to:			
<ul style="list-style-type: none"> • Learn circuit-oriented approach towards digital design • Illustrate the impact of interconnect wiring on the functionality and performance of a digital gate. • Infer different approaches to digital timing and clocking circuits • Understand the impact of clock skew on the behaviour of digital synchronous circuits • Explain the role of peripheral circuitry such as the decoders, sense amplifiers, drivers and control circuitry in the design of reliable and fast memories 			
Modules			RBT Level
Module 1			
Implementation Strategies For Digital ICS: Introduction, From Custom to Semicustom and Structured Array Design Approaches, Custom Circuit Design, Cell-Based Design Methodology, Standard Cell, Compiled Cells, Macrocells, Megacells and Intellectual Property, Semi-Custom Design Flow, Array-Based Implementation Approaches, Pre-diffused (or Mask-Programmable) Arrays, Pre-wired Arrays, Perspective-The Implementation Platform of the Future.			L1,L2,L3
Module 2			
Coping With Interconnect: Introduction, Capacitive Parasitics, Capacitance and Reliability-Cross Talk, Capacitance and Performance in CMOS, Resistive Parasitics, Resistance and Reliability-Ohmic Voltage Drop, Electromigration, Resistance and Performance-RC Delay, Inductive Parasitics, Inductance and Reliability-Voltage Drop, Inductance and Performance-Transmission Line Effects, Advanced Interconnect Techniques, Reduced-Swing Circuits, Current-Mode Transmission Techniques, Perspective: Networks-on-a-Chip.			L1,L2,L3
Module 3			
Timing Issues In Digital Circuits: Introduction, Timing Classification of Digital Systems, Synchronous Interconnect, Mesochronous interconnect, Plesiochronous Interconnect, Asynchronous Interconnect, Synchronous Design — An In-depth Perspective, Synchronous Timing Basics, Sources of Skew and Jitter, Clock-Distribution Techniques, Latch-Based Clocking, Self-Timed Circuit Design, Self-Timed Logic - An Asynchronous			L1,L2,L3

Technique, Completion-Signal Generation, Self-Timed Signaling, Practical Examples of Self-Timed Logic, Synchronizers and Arbiters, Synchronizers-Concept and Implementation, Arbiters, Clock Synthesis and Synchronization Using a Phase-Locked Loop, Basic Concept, Building Blocks of a PLL.	
Module 4	
Designing Memory and Array Structures: Introduction, Memory Classification, Memory Architectures and Building Blocks, The Memory Core, Read-Only Memories, Nonvolatile Read-Write Memories, Read-Write Memories (RAM), Contents-Addressable or Associative Memory (CAM), Memory Peripheral Circuitry, The Address Decoders, Sense Amplifiers, Voltage References, Drivers/Buffers, Timing and Control.	L1,L2,L3
Module 5	
Designing Memory and Array Structures: Memory Reliability and Yield, Signal-to-Noise Ratio, Memory yield, Power Dissipation in Memories, Sources of Power Dissipation in Memories, Partitioning of the memory, Addressing the Active Power Dissipation, Data-retention dissipation, Case Studies in Memory Design: The Programmable Logic Array (PLA), A 4 Mbit SRAM, A 1 Gbit NAND Flash Memory, Perspective: Semiconductor Memory Trends and Evolutions.	L1,L2,L3
<p>Course Outcomes: After studying this course, students will be able to:</p> <ul style="list-style-type: none"> • Apply design automation for complex circuits using the different implementation methodology like custom versus semi-custom, hardwired versus fixed, regular array versus ad-hoc. • Use the approaches to minimize the impact of interconnect parasitics on performance, power dissipation and circuit reliability • Impose the ordering of the switching events to meet the desired timing constraints using synchronous, clocked approach. • Infer the reliability of the memory 	
<p>Question paper pattern:</p> <ul style="list-style-type: none"> • The question paper will have 10 full questions carrying equal marks. • Each full question consists of 16 marks with a maximum of four sub questions. • There will be 2 full questions from each module covering all the topics of the module • The students will have to answer 5 full questions, selecting one full question from each module. 	
<p>Text Book:</p> <p>Jan M Rabey, Anantha Chandrakasan, Borivoje Nikolic, “Digital Integrated Circuits-A Design Perspective”, PHI, 2nd Edition.</p>	
<p>Reference Books:</p> <ol style="list-style-type: none"> 1. M. Smith, “Application Specific Integrated circuits”, Addison Wesley, 1997 2. H. Veendrick, “MOS IC’s: From Basics to ASICs, Wiley-VCH, 1992. 3. Anantha P. Chandrakasan , Robert W. Brodersen, “Low Power Digital CMOS Design”, Kluwer Academic Publisher, 1995. 	

Real Time Operating System			
[As per Choice Based credit System (CBCS) Scheme SEMESTER – II			
Subject Code	16EVE24	IA Marks	20
Number of Lecture Hours/Week	04	Exam marks	80
Total Number of Lecture Hours	50 (10 Hours per Module)	Exam Hours	03
CREDITS – 04			
Course Objectives: This course will enable the students to:			
<ul style="list-style-type: none"> • Introduce the fundamental concepts of Real Time Operating Systems and the real time embedded system • Apply concepts relating to operating systems such as Scheduling techniques, Thread Safe Reentrant Functions, Dynamic priority policies. • Describe concepts related to Multi resource services like blocking, Deadlock, live lock & soft real-time services. • Discuss Memory management concepts, Embedded system components, Debugging components and file system components. • Study programs for multithreaded applications using suitable data structures. 			
Modules			RBT Level
Module 1			
Real-Time Systems and Resources: Brief history of Real Time Systems, A brief history of Embedded Systems. System Resources, Resource Analysis, Real-Time Service Utility, Scheduler concepts, Real-Time OS, State transition diagram and tables, Thread Safe Reentrant Functions. (Text 1: Selected sections from Chap. 1, 2)			L1,L2,L3
Module 2			
Processing with Real Time Scheduling: Scheduler Concepts, Preemptive Fixed Priority Scheduling Policies with timing diagrams and problems and issues, Feasibility, Rate Monotonic least upper bound, Necessary and Sufficient feasibility, Deadline –Monotonic Policy, Dynamic priority policies, Alternative to RM policy. (Text 1: Chap. 2,3,7)			L1,L2,L3
Module 3			
Memory and I/O: Worst case execution time, Intermediate I/O, Shared Memory, ECC Memory, Flash file systems. Multi-resource Services, Blocking, Deadlock and live lock, Critical sections to protect shared resources, Missed deadline, QoS, Reliability and Availability, Similarities and differences, Reliable software, Available software. (Text 1: Selected topics from Chap. 4,5,6,7,11)			L1,L2,L3
Module 4			
Firmware Components: The 3 firmware components, RTOS system software mechanisms, Software application components. Debugging			L1,L2,L3

<p>Components, Exceptions, assert, Checking return codes, Single-step debugging, kernel scheduler traces, Test access ports, Trace Ports, External test equipment. (Text 1: Selected topics from Chap. 8,9)</p>	
<p>Module 5</p>	
<p>Process and Threads: Process and thread creations, Simple Programs, Programs related to semaphores, message queue, shared buffer applications involving inter task/thread communication using multiple threads. (Text 2: Chap. 11)</p>	<p>L1,L2,L3</p>
<p>Course Outcomes: After studying this course, students will be able to:</p> <ul style="list-style-type: none"> • Develop programs for real time services, firmware and RTOS, using the fundamentals of Real Time Embedded System, real time service utilities, debugging methodologies and optimization techniques. • Select the appropriate system resources (CPU, I/O, Memory, Cache, ECC Memory, Microcontroller/FPGA/ASIC to improve the system performance. • Apply priority based static and dynamic real time scheduling techniques for the given specifications. • Analyze deadlock conditions, shared memory problem, critical section problem, missed deadlines, availability, reliability and QoS. • Develop programs for multithreaded applications using suitable techniques and data structure 	
<p>Question paper pattern:</p> <ul style="list-style-type: none"> • The question paper will have 10 full questions carrying equal marks. • Each full question consists of 16 marks with a maximum of four sub questions. • There will be 2 full questions from each module covering all the topics of the module • The students will have to answer 5 full questions, selecting one full question from each module. 	
<p>Text Books:</p> <ol style="list-style-type: none"> 1. Sam Siewert, “Real-Time Embedded Systems and Components”, Cengage Learning India Edition, 2007. 2. Dr. K.V.K.K Prasad, Embedded/Real Time Systems, Concepts, Design and Programming, Black Book, Dream Tech Press, New edition, 2010. 	
<p>Reference Books:</p> <ol style="list-style-type: none"> 1. James W S Liu, “Real Time System”, Pearson education, 2008. 2. Dream Tech Software Team, “Programming for Embedded Systems”, John Wiley, India Pvt. Ltd., 2008. 	

System Verilog [As per Choice Based credit System (CBCS) Scheme SEMESTER – II			
Subject Code	16EVE251	IA Marks	20
Number of Lecture Hours/Week	03	Exam marks	80
Total Number of Lecture Hours	40 (8 Hours per Module)	Exam Hours	03
CREDITS – 03			
Course Objectives: This course will enable students to:			
<ul style="list-style-type: none"> • Understand digital system verification using object oriented methods • Learn the System Verilog language for digital system verification. • Create/build test benches for the basic design/methodology. • Use constrained random tests for verification • Understand concepts of functional coverage 			
Modules			RBT Level
Module 1			
Verification Guidelines: The verification process, basic test bench functionality, directed testing, methodology basics, constrained random stimulus, randomization, functional coverage, test bench components.			L1, L2
Data Types: Built in Data types, fixed and dynamic arrays, Queues, associative arrays, linked lists, array methods, choosing a storage type, creating new types with type def, creating user defined structures, type conversion, Enumerated types, constants and strings, Expression width.			
Module 2			
Procedural Statements and Routines: Procedural statements, Tasks, Functions and void functions, Task and function overview, Routine arguments, returning from a routine, Local data storage, time values.			L1,L2,L3
Converting the test bench and design: Separating the test bench and design, The interface construct, Stimulus timing, Interface driving and sampling, System Verilog assertions.			
Module 3			
Randomization: Introduction, Randomization in System Verilog, Constraint details, Solution probabilities, Valid constraints, In-line constraints, Random number functions, Common randomization problems, Iterative and array constraints, Random control.			L1,L2,L3
Module 4			
Threads and Interprocess Communication: Working with threads, Disabling threads, Interprocess			L1,L2,L3

communication, Events, semaphores, Mailboxes, Building a test bench with threads and Interprocess Communication.	
Module 5	
Functional Coverage: Coverage types, Coverage strategies, Simple coverage example, Anatomy of Cover group and Triggering a Cover group, Data sampling, Cross coverage, Generic Cover groups, Coverage options, Analyzing coverage data, measuring coverage statistics during simulation.	L1,L2,L3
Course Outcomes: After studying this course, students will be able to: <ul style="list-style-type: none"> • Write test benches for moderately complex digital circuits • Use System Verilog language • Appreciate functional coverage • Apply constrained random tests benches using System Verilog • Analyze a verification case and apply System Verilog to verify the design 	
Question paper pattern: <ul style="list-style-type: none"> • The question paper will have 10 full questions carrying equal marks. • Each full question consists of 16 marks with a maximum of four sub questions. • There will be 2 full questions from each module covering all the topics of the module • The students will have to answer 5 full questions, selecting one full question from each module. 	
Text Book: Chris Spear, ‘System Verilog for Verification – A guide to learning the Test bench language features’, Springer Publications, 2 nd Edition, 2010.	
Reference Book: Stuart Sutherland, Simon Davidmann, Peter Flake, “System Verilog for Design- A guide to using system verilog for Hardware design and modeling”, Springer Publications, 2 nd Edition, 2006.	

VLSI Design for Signal Processing [As per Choice Based credit System (CBCS) Scheme SEMESTER – II			
Subject Code	16EVE252	IA Marks	20
Number of Lecture Hours/Week	03	Exam marks	80
Total Number of Lecture Hours	40 (8 Hours per Module)	Exam Hours	03
CREDITS – 03			
Course Objectives: This course will enable students to: <ul style="list-style-type: none"> Learn several high-level architectural transformations that can be used to design families of architectures for a given algorithm. Deal with high-level algorithm transformations such as strength reduction, look-ahead and relaxed look-ahead. 			
Modules			RBT Level
Module 1			
Introduction to DSP Systems: Typical DSP Algorithms, DSP Application Demands and Scaled CMOS Technologies, Representations of DSP Algorithms. Iteration Bounds: Data flow graph Representations, loop bound and Iteration bound.			L1, L2
Module 2			
Iteration Bounds: Algorithms for Computing Iteration Bound, Iteration Bound of multi rate data flow graphs. Pipelining and Parallel Processing: pipelining of FIR Digital Filters, parallel processing, Pipelining and parallel processing for low power.			L1,L2,L3
Module 3			
Retiming: Definition and Properties, Solving Systems of Inequalities, Retiming Techniques, Unfolding: An Algorithm for Unfolding, Properties of Unfolding, Critical path, Unfolding and Retiming, Application of Unfolding. Systolic Architecture Design: systolic array design Methodology, FIR systolic array.			L1,L2,L3
Module 4			
Systolic Architecture Design: Selection of Scheduling Vector, Matrix-Matrix Multiplication and 2D systolic Array Design, Systolic Design for space representation containing Delays. Fast convolution: Cook-Toom Algorithm, Winograd Algorithm, Iterated convolution, cyclic convolution Design of fast convolution Algorithm by Inspection.			L1,L2,L3
Module 5			
Pipelined and Parallel Recursive and Adaptive Filter: Pipeline Interleaving in Digital Filter, first order IIR digital Filter, Higher order IIR digital Filter, parallel processing for IIR filter, Combined pipelining and parallel processing for IIR Filter, Low power IIR Filter Design Using Pipelining and parallel processing, pipelined adaptive			L1,L2,L3

digital filter.

Course Outcomes: After studying this course, students will be able to:

- Illustrate the use of various DSP algorithms and addresses their representation using block diagrams, signal flow graphs and data-flow graphs
- Use pipelining and parallel processing in design of high-speed /low-power applications
- Apply unfolding in the design of parallel architecture
- Evaluate the use of look-ahead techniques in parallel and pipelined IIR Digital filters.
- Develop an algorithm or architecture or circuit design for DSP applications

Question paper pattern:

- The question paper will have 10 full questions carrying equal marks.
- Each full question consists of 16 marks with a maximum of four sub questions.
- There will be 2 full questions from each module covering all the topics of the module
- The students will have to answer 5 full questions, selecting one full question from each module.

Text Book:

Keshab K.Parthi, "VLSI Digital Signal Processing systems, Design and implementation ", Wiley 1999.

Reference Books:

1. Mohammed Isamail and Terri Fiez, "Analog VLSI Signal and Information Processing ", Mc Graw-Hill,1994.
2. S.Y. Kung, H.J. White House, T. Kailath, " VLSI and Modern Signal Processing ", Prentice Hall, 1985.
3. Jose E. France, Yannis Tsvividis, " Design of Analog - Digital VLSI Circuits for Telecommunication and Signal Processing ", Prentice Hall, 1994.
4. Lars Wanhammar, "DSP Integrated Circuits", Academic Press Series in Engineering, 1st Edition.

Micro Electro Mechanical Systems [As per Choice Based credit System (CBCS) Scheme SEMESTER – II			
Subject Code	16ELD253	IA Marks	20
Number of Lecture Hours/Week	04	Exam marks	80
Total Number of Lecture Hours	40 (08 Hours per Module)	Exam Hours	03
CREDITS – 03			
Course Objectives: This course will enable students to:			
<ul style="list-style-type: none"> • Know an overview of microsystems, their fabrication and application areas. • Teach working principles of several MEMS devices. • Develop mathematical and analytical models of MEMS devices • Know methods to fabricate MEMS devices • Expose the students to various application areas where MEMS devices can be used. 			
Modules			RBT Level
Module 1			
Overview of MEMS and Microsystems: MEMS and Microsystem, Typical MEMS and Microsystems Products, Evolution of Microfabrication, Microsystems and Microelectronics, Multidisciplinary Nature of Microsystems, Miniaturization. Applications and Markets.			L1, L2
Module 2			
Working Principles of Microsystems: Introduction, Microsensors, Microactuation, MEMS with Microactuators, Microaccelerometers, Microfluidics.			L1, L2
Engineering Science for Microsystems Design and Fabrication: Introduction, Atomic Structure of Matters, Ions and Ionization, Molecular Theory of Matter and Inter-molecular Forces, Doping of Semiconductors, The Diffusion Process, Plasma Physics, Electrochemistry.			
Module 3			
Engineering Mechanics for Microsystems Design: Introduction, Static Bending of Thin Plates, Mechanical Vibration, Thermomechanics, Fracture Mechanics, Thin Film Mechanics, Overview on Finite Element Stress Analysis.			L1,L2,L3
Module 4			
Scaling Laws in Miniaturization: Introduction, Scaling in Geometry, Scaling in Rigid-Body Dynamics, Scaling in Electrostatic Forces, Scaling of Electromagnetic Forces, Scaling in Electricity, Scaling in Fluid Mechanics, Scaling in Heat Transfer.			L1,L2,L3

Module 5	
<p>Overview of Micro-manufacturing: Introduction, Bulk Micro-manufacturing, Surface Micromachining, The LIGA Process, Summary on Micro-manufacturing.</p> <p>Microsystem Design: Introduction, Design Considerations, Process Design, Mechanical Design, Using Finite Element Method.</p>	L1,L2,L3
<p>Course Outcomes: After studying this course, students will be able to:</p> <ul style="list-style-type: none"> • Appreciate the technologies related to Micro Electro Mechanical Systems. • Understand design and fabrication processes involved with MEMS devices. • Analyse the MEMS devices and develop suitable mathematical models • Know various application areas for MEMS devices 	
<p>Question paper pattern:</p> <ul style="list-style-type: none"> • The question paper will have 10 full questions carrying equal marks. • Each full question consists of 16 marks with a maximum of four sub questions. • There will be 2 full questions from each module covering all the topics of the module • The students will have to answer 5 full questions, selecting one full question from each module. 	
<p>Text Book: Tai-Ran Hsu, MEMS and Micro systems: Design, Manufacture and Nanoscale Engineering, 2nd Ed, Wiley.</p>	
<p>Reference Books:</p> <ol style="list-style-type: none"> 1. Hans H. Gatzert, Volker Saile, Jurg Leuthold, Micro and Nano Fabrication: Tools and Processes, Springer, 2015. 2. Dilip Kumar Bhattacharya, Brajesh Kumar Kaushik, Micro electromechanical Systems (MEMS), Cengage Learning. 	

SoC Design			
[As per Choice Based credit System (CBCS) Scheme SEMESTER – II			
Subject Code	16EVE254	IA Marks	20
Number of Lecture Hours/Week	03	Exam marks	80
Total Number of Lecture Hours	40 (8 Hours per Module)	Exam Hours	03
CREDITS – 03			
<p>Course Objectives: This course will enable students to:</p> <ul style="list-style-type: none"> • Describe the ARM processor architecture and user-level assembly language programming • Appreciate what a high-level language (in this case, C) really needs and how those needs are met by the ARM instruction set. • raises the issues involved in debugging systems which use embedded processor cores and in the production testing of board-level systems. • Learn the concept of memory hierarchy, discussing the principles of memory management and caches. 			
Modules			RBT Level
Module 1			
<p>ARM Organization and Implementation: 3-stage pipeline ARM organization, 5-stage pipeline ARM organization, ARM instruction execution, ARM implementation, The ARM coprocessor interface.</p> <p>The ARM Instruction Set : Introduction, Exceptions, Conditional execution, Branch and Branch with Link (B, BL), Branch with Link and eXchange (BX, BLX), Software Interrupt (SWI), Data processing instructions, Multiply instructions, Count leading zeros (CLZ - architecture v5T only), Single word and unsigned byte data transfer instruction, Half-word and signed byte data transfer instructions, Multiple register transfer instructions, Swap memory and register instructions (SWP), Status register to general register transfer instructions, General register to status register transfer instructions, Coprocessor instructions, Coprocessor data operations, Coprocessor data transfers, Coprocessor register transfers, Breakpoint instruction (BRK - architecture v5T only), Unused instruction space, Memory faults, ARM architecture variants.</p>			L1,L2
Module 2			
<p>Architectural Support for High-Level Languages: Abstraction in software design, Data types, Floating-point data types, The ARM floating-point architecture, Expressions, Conditional statements, Loops, Functions and procedures, Use of memory, Run-time environment.</p> <p>Architectural Support for System Development: The ARM memory interface, The Advanced Microcontroller Bus Architecture (AMBA), The ARM reference peripheral specification, Hardware system prototyping tools, The ARMulator, The JTAG boundary scan test architecture, The ARM debug architecture, Embedded Trace,</p>			L1,L2

Signal processing support.	
Module 3	
ARM Processor Cores: ARM7TDMI, ARM8,ARM9TDMI, ARM10TDMI ,Discussion ,Example and exercises. Memory Hierarchy: Memory size and speed, On-chip memory, Caches, Cache design - an example, Memory management, Examples and exercises.	L1,L2
Module 4	
Architectural Support for Operating Systems: An introduction to operating systems, The ARM system control coprocessor, CP15 protection unit registers, ARM protection unit,CP15 MMU registers, ARM MMU architecture, Synchronization, Context switching, Input/ Output, Example and exercises. ARM CPU Cores: The ARM710T, ARM720T and ARM740T, The ARM810,The Strong ARM SA-110,The ARM920T and ARM940T,The ARM946E-S and ARM966E-S,The ARM1020E,Discussion,Example and exercises.	L1,L2
Module 5	
Embedded ARM Applications: The VLSI Ruby II Advanced Communication Processor, The VLSI ISDN Subscriber Processor, The One C™ VWS22100 GSM chip, The Ericsson-VLSI Bluetooth Baseband Controller, The ARM7500 and ARM7500FE, The ARM7100 364,The SA-1100 368,Examples and exercises. The AMULET Asynchronous ARM Processors: Self-timed design 375,AMULET1 377,AMULET2 381,AMULET2e 384,AMULET3 387,The DRACO telecommunications controller 390, A self-timed future? 396,Example and exercises.	L1,L2,L3
Course Outcomes: After studying this course, students will be able to: <ul style="list-style-type: none"> • Apply the 3- and 5-stage pipeline ARM processor cores and analyse the implementation issues. • Use the concepts and methodologies employed in designing a System-on-chip (SoC) based around a microprocessor core and in designing the microprocessor core itself. • Understand how SoCs and microprocessors are designed and used, and why a modern processor is designed the way that it is. • Use integrated ARM CPU cores (including StrongARM) that incorporate full support for memory management. • Analyze the requirements of a modern operating system and use the ARM architecture to address the same. 	
Question paper pattern: <ul style="list-style-type: none"> • The question paper will have 10 full questions carrying equal marks. • Each full question consists of 16 marks with a maximum of four sub questions. • There will be 2 full questions from each module covering all the topics of the module • The students will have to answer 5 full questions, selecting one full question from each module. 	
Text Book: Steve Furber, “ARM System-On-Chip Architecture”, Addison Wesley, 2nd edition.	

References Books:

1. Joseph Yiu, "The Definitive Guide to the ARM Cortex-M3", 2nd edn, Newnes, (Elsevier), 2010.
2. Sudeep Pasricha and Nikil Dutt, "On-Chip Communication Architectures: System on Chip Interconnect", Morgan Kaufmann, Publishers © 2008.
3. Michael Keating, Pierre Bricaud, "Reuse Methodology Manual for System on Chip designs", Kluwer Academic Publishers, 2nd edition, 2008.

VLSI and ES Lab-2			
[As per Choice Based Credit System (CBCS) scheme]			
SEMESTER – II			
Laboratory Code	16EVEL26	IA Marks	20
Number of Lecture Hours/Week	03	Exam marks	80
Total Number of Lecture Hours	01Hr Tutorial (Instructions) + 02 Hours Laboratory	Exam Hours	03
CREDITS – 02			
<p>Course objectives: This laboratory course enables students to:</p> <ul style="list-style-type: none"> • Learn the CAD tool and the flow of the Full Custom IC design cycle. • Learn running DRC, LVS and Parasitic Extraction of the various designs. • Create various components like inverter, differential amplifier and use the same in the design of operational amplifier, R-2R based DAC and ADC. • Understand the suitability of different techniques of IPC and task switching in a multithreaded application. • Study and implement different types of data structures required to implement inter task communication. • Implement Inter task communication using an appropriate data structure. 			
Part – A: Experiments to be done using CADENCE/SYNOPSIS/MENTOR GRAPHICS/TANNER Tool			RBT Level
<p>1. Design an Inverter with given specifications*, completing the design flow mentioned below:</p> <ol style="list-style-type: none"> a. Draw the schematic and verify the following <ol style="list-style-type: none"> i) DC Analysis ii) Transient Analysis b. Draw the Layout and verify the DRC, ERC c. Check for XX d. Extract RC and back annotate the same and verify the Design e. Verify & Optimize for Time, Power and Area to the given constraint*** <p>(Following specification may be used to design an Inverter in gpdk 180nm technology with minimum area:</p> <ol style="list-style-type: none"> i. Maximum output rise time=100ps ii. Maximum output fall time=100ps iii. $P_{avg} \leq 15\mu w$ iv. Load capacitance= 50fF v. Input rise time=200ps vi. Input fall time=200ps <p>Choose maximum frequency based on the power)</p>			L3
<p>Design the following circuits with given specifications*, completing the design flow mentioned below:</p> <ol style="list-style-type: none"> a. Draw the schematic and verify the following <ol style="list-style-type: none"> i) DC Analysis ii) AC Analysis iii) Transient Analysis 			L3

<p>b. Draw the Layout and verify the DRC, ERC, LVS c. Check for XX d. Extract RC and back annotate the same and verify the Design.</p> <p>2. i) A Single Stage differential amplifier ii) Common source amplifier</p> <p>3. Design an op-amp with given specification* using given differential amplifier Common source amplifier in library**</p> <p>4. Design a 4 bit R-2R based DAC for the given specification**</p> <p>5. Design an Integrator and Differentiator using OPAMP (First Order)</p> <p>6. Design and characterize a basic Sigma delta ADC from the available designs.</p> <p>7. Design a simple NAND/NOR gate using any one of the tools given above.</p> <p>(Any other experiments may be added in supportive of the course) * Appropriate specification should be given. ** Applicable Library should be added & information should be given to the Designer. *** An appropriate constraint should be given</p>	
Part – B: Experiments to be done using Linux	
<p>1. Develop and test programs to (a) create child process and display it's id and (b) Execute child process function using switch structure</p>	
<p>2. Develop and test program for a multithreaded application, where communication is through a buffer for the conversion of lowercase text to uppercase text, using semaphore concept.</p>	
<p>3. Develop and test program for a multithreaded application, where communication is through shared memory for the conversion of lowercase text to uppercase text.</p>	
<p>4. Develop program for inter-thread communication using message queue. Data is to be input from the keyboard for the chosen application.</p>	
<p>5. Create 'n' number of child threads. Each thread prints the message "I'm in thread number ..." and sleeps for 50 ms and then quits. The main thread waits for complete execution of all the child threads and then quits. Compile and execute in Linux.</p>	
<p>6. Implement the multi-thread application satisfying the following :</p> <p>i. Two child threads are created with normal priority.</p> <p>ii. Thread 1 receives and prints its priority and sleeps for 50ms and then quits.</p> <p>iii. Thread 2 prints the priority of the thread 1 and rises its priority to above normal and retrieves the new priority of thread 1, prints it and then quits.</p> <p>iv. The main thread waits for the child thread to complete its job and</p>	L3

quits.	
7. Implement the usage of anonymous pipe with 512 bytes for data sharing between parent and child processes using handle inheritance mechanism	
<p>Course outcomes: This laboratory course enable the students to:</p> <ul style="list-style-type: none"> • Design Analog, digital and mixed mode circuits • Learn the various issues in Mixed signal designs basically data converters. • Acquire hands-on skills of using CAD tools in VLSI design. • Appreciate the design process in VLSI through a mini-project on the design of a CMOS sub-system. • Select a suitable task switching technique in a multithreaded application. • Implement different techniques of message passing and Inter task communication. • Implement different data structures such as pipes, queues and buffers in multithreaded programming. 	
<p>Conduct of Practical Examination:</p> <ul style="list-style-type: none"> • All laboratory experiments are to be included for practical examination. • For examination, one experiment from Part-A and One experiment from Part-B is to be set. • Strictly follow the instructions as printed on the cover page of answer script for breakup of marks. • Change of experiment is allowed only once and Marks allotted to the Procedure part to be made zero. 	
<p>Reference Book: (for some of the Part-B programs) Dreamtech Software Team, “Programming for Embedded Systems”, John Wiley, India Pvt. Ltd., 2008.</p>	

M.Tech-VLSI & ES-2016-FOURTH SEMESTER SYLLABUS

Synthesis and Optimization of Digital Circuits [As per Choice Based credit System (CBCS) Scheme SEMESTER – IV			
Subject Code	16ELD41	IA Marks	20
Number of Lecture Hours/Week	04	Exam marks	80
Total Number of Lecture Hours	50 (10 Hours per Module)	Exam Hours	03
CREDITS – 04			
<p>Course Objectives: This course will enable students:</p> <ul style="list-style-type: none"> • Understand the need for optimization and dimensions of optimization for digital circuits. • Understand basic optimization techniques used in circuits design • Understand advanced tools and techniques in digital systems design including Hardware Modeling and Compilation Techniques. • Explain details of Logic-Level synthesis and optimization techniques for combinational and sequential circuits. • Explain the concept of scheduling and resource binding for optimization. 			
Modules			RBT Level
Module 1			
<p>Introduction to Synthesis and optimization: Design of Microelectronics circuits, Computer aided Synthesis and Optimization.</p> <p>Hardware Modeling: HDLs for Synthesis, Abstract models, Compilation and Behavioral Optimization. (Text1: Topics from Chap. 1,3)</p>			L1, L2, L3
Module 2			
<p>Graph theory for CAD for VLSI: Graphs, Combinatorial Optimization, Graph Optimization problems and Algorithms, Boolean Algebra and Applications.</p> <p>Architectural Synthesis and Optimization: Fundamental Architectural Synthesis problems, Area and Performance Estimation, Strategies for Architectural Optimization, Data path Synthesis, Control Path Synthesis.(Text1: Topics From Chap. 2,4)</p>			L1, L2, L3
Module 3			
<p>Two level Combinational Logic Optimization: Introduction, Logic Optimizations, Operations on Two level Logic Covers, Algorithms for Logic Minimization, Symbolic Minimization and Encoding Problems.</p> <p>Multiple Level Combinational Logic Optimization: Introduction, Models and Transformations for Combinational Networks, The Algebraic Model, The Boolean Model. (Text1: Chap. 7, 8)</p>			L1, L2, L3
Module 4			
<p>Sequential Logic Optimization: Introduction, Sequential Logic Optimization using State based Models, Sequential Logic Optimization using Network Models, Implicit FSM Traversal Methods, Testability concerns for</p>			L1, L2, L3

Synchronous Circuits. (Text 1: Chap. 9)	
Module 5	
<p>Scheduling Algorithms: Introduction, A Model for Scheduling problems, Scheduling with Resource Constraints, Scheduling without Resource Constraints, Scheduling Algorithms for Extended Sequencing Models, Scheduling Pipelined Circuits.</p> <p>Resource Sharing and Binding: Sharing and Binding for Resource dominated circuits, Sharing and Binding for General Circuits, Concurrent Binding and Scheduling, Resource sharing and Binding for Non – Scheduled Sequencing Graphs. (Text1: Chap. 5,6)</p>	L1, L2, L3
<p>Course Outcomes: After studying this course, students will be able to:</p> <ul style="list-style-type: none"> • Understand the process of synthesis and optimization in a top down approach for digital circuits models using HDLs. • Understand the terminologies of graph theory and its algorithms to optimize a Boolean equation. • Apply different two level and multilevel optimization algorithms for combinational circuits • Apply the different sequential circuit optimization methods using state models and network models. • Apply different scheduling algorithms with resource binding and without resource binding for pipelined sequential circuits and extended sequencing models. 	
<p>Question paper pattern:</p> <ul style="list-style-type: none"> • The question paper will have 10 full questions carrying equal marks. • Each full question consists of 16 marks with a maximum of four sub questions. • There will be 2 full questions from each module covering all the topics of the module • The students will have to answer 5 full questions, selecting one full question from each module. 	
<p>Text Book: Giovanni De Micheli, “Synthesis and Optimization of Digital Circuits”, Tata McGraw-Hill, 2003.</p>	
<p>Reference Book: Edwards M.D., Automatic Logic synthesis Techniques for Digital Systems, Macmillan New Electronic Series, 1992.</p>	

CMOS RF Circuit Design

[As per Choice Based credit System (CBCS) Scheme
SEMESTER – IV

Subject Code	16EVE421	IA Marks	20
Number of Lecture Hours/Week	03	Exam marks	80
Total Number of Lecture Hours	40 (8 Hours per Module)	Exam Hours	03

CREDITS – 03

Course Objectives: This course will enable students to:

- Learn basic concepts in RF and microwave design emphasising the effects of nonlinearity and noise.
- Appreciate communication system, multiple access and wireless standards necessary for RF circuit design.
- Deal with transceiver architecture, various receiver and transmitter designs, their merits and demerits
- Understand the design of RF building blocks such as Low Noise Amplifiers and Mixers

Modules

**RBT
Level**

Module 1

Introduction to RF Design and Wireless Technology:

Basic concepts in RF design(I): General considerations, Effects of Nonlinearity, Noise, Sensitivity and dynamic range

L1,L2,L3

Module 2

Basic concepts in RF design (II): Passive impedance transformation, scattering parameters, analysis of nonlinear dynamic systems

L1,L2,L3

Module 3

Communication Concepts: General concepts, analog modulation, digital modulation, spectral re-growth, Mobile RF communications, Multiple access techniques, Wireless standards

L1,L2,L3

Module 4

Transceiver Architecture (I): General considerations, Receiver architecture,

L1,L2,L3

Module 5

Transceiver Architecture (II): Transmitter architectures
Low Noise Amplifiers: LNA topologies: common-source stage with inductive load, common-source stage with resistive feedback.
Mixers: General considerations, passive down conversion mixers.

L1,L2,L3

Course Outcomes: After studying this course, students will be able to:

1. Analyse the effect of nonlinearity and noise in RF and microwave design.
2. Exemplify the approaches taken in actual RF products.
3. Minimize the number of off-chip components required to design mixers and Low-Noise Amplifiers.
4. Explain various receivers and transmitter topologies with their merits and

drawbacks.

5. Demonstrate how the system requirements define the parameters of the circuits and how the performance of each circuit impacts that of the overall transceiver.

Question paper pattern:

- The question paper will have 10 full questions carrying equal marks.
- Each full question consists of 16 marks with a maximum of four sub questions.
- There will be 2 full questions from each module covering all the topics of the module
- The students will have to answer 5 full questions, selecting one full question from each module.

Text Book:

B. Razavi, "**RF Microelectronics**", PHI, second edition.

Reference Books:

1. R. Jacob Baker, H.W. Li, D.E. Boyce "**CMOS Circuit Design, layout and Simulation**", PHI 1998.
2. Thomas H. Lee "**Design of CMOS RF Integrated Circuits**" Cambridge University press 1998.
3. Y.P. Tsividis, "**Mixed Analog and Digital Devices and Technology**", TMH 1996

Advances in Image Processing			
[As per Choice Based credit System (CBCS) Scheme SEMESTER – IV			
Subject Code	16ECS422	IA Marks	20
Number of Lecture Hours/Week	03	Exam marks	80
Total Number of Lecture Hours	40 (8 Hours per Module)	Exam Hours	03
CREDITS – 03			
Course Objectives: This course will enable students to:			
<ul style="list-style-type: none"> • Acquire fundamental knowledge in understanding the representation of the digital image and its properties • Equip with some pre-processing techniques required to enhance the image for further analysis purpose. • Select the region of interest in the image using segmentation techniques. • Represent the image based on its shape and edge information. • Describe the objects present in the image based on its properties and structure. 			
Modules			RBT Level
Module 1			
The image, its representations and properties: Image representations a few concepts, Image digitization, Digital image properties, Color images.			L1
Module 2			
Image Pre-processing: Pixel brightness transformations, geometric transformations, local pre-processing.			L1, L2
Module 3			
Segmentation: Thresholding; Edge-based segmentation – Edge image thresholding, Edge relaxation, Border tracing, Hough transforms; Region – based segmentation – Region merging, Region splitting, Splitting and merging, Watershed segmentation, Region growing post-processing.			L1, L2, L3
Module 4			
Shape representation and description: Region identification; Contour-based shape representation and description – Chain codes, Simple geometric border representation, Fourier transforms of boundaries, Boundary description using segment sequences, B-spline representation; Region-based shape representation and description – Simple scalar region descriptors, Moments, Convex hull.			L1, L2, L3
Module 5			
Mathematical Morphology: Basic morphological concepts, Four morphological principles, Binary dilation and erosion, Skeletons and object marking, Morphological segmentations and watersheds.			L1, L2, L3
Course Outcomes: After studying this course, students will be able to:			
<ul style="list-style-type: none"> • Understand the representation of the digital image and its properties • Apply pre-processing techniques required to enhance the image for its further analysis. 			

- Use segmentation techniques to select the region of interest in the image for analysis
- Represent the image based on its shape and edge information.
- Describe the objects present in the image based on its properties and structure.
- Use morphological operations to simplify images, and quantify and preserve the main shape characteristics of the objects.

Question paper pattern:

- The question paper will have 10 full questions carrying equal marks.
- Each full question consists of 16 marks with a maximum of four sub questions.
- There will be 2 full questions from each module covering all the topics of the module
- The students will have to answer 5 full questions, selecting one full question from each module.

Text Books:

1. Milan Sonka, Vaclav Hlavac, Roger Boyle, “Image Processing, Analysis, and Machine Vision”, Cengage Learning, 2013, ISBN: 978-81-315-1883-0

Reference Books:

1. Geoff Dougherty, Digital Image Processing for Medical Applications, Cambridge university Press, 2010
2. S.Jayaraman, S Esakkirajan, T.Veerakumar, Digital Image Processing, Tata McGraw Hill, 2011

High Speed VLSI Design [As per Choice Based credit System (CBCS) Scheme SEMESTER – IV			
Subject Code	16EVE423	IA Marks	20
Number of Lecture Hours/Week	03	Exam marks	80
Total Number of Lecture Hours	40 (8 Hours per Module)	Exam Hours	03
CREDITS – 03			
<p>Course Objectives: This course will enable students to:</p> <ul style="list-style-type: none"> • Learn sources of process – driven performance variation in quarter-micron CMOS and apply the rules of thumb. • Comprehend non-clocked static circuit families, used to implement combinatorial logic. • Interpret the design styles used for clocked and non-clocked systems. • Explore the design parameters such as on-chip device length tolerance, supply rail inconsistency and temperature variations. 			
Modules			RBT Level
Module 1			
Process Variability: Introduction, Front-end -of-line variability considerations, charge loss mechanisms, back-end-of- line variability considerations.			L1, L2
Module 2			
Non-Clocked logic styles: Introduction, static CMOS structures, DC VS logic, Non-clocked pass-gate families. Clocked logic styles: Introduction, single-rail domino logic styles. Dual-rail domino structures, latched domino structures, clocked-pass gate logic.			L1, L2,L3
Module 3			
Circuit Design margin and design variability: Introduction, process induced variation, design induced variations, and application induced variations’, Noise. Latching Strategies: Introduction, basic latch design, latching single ended logic, latching differential logic, race-free latched for pre-charge logic.			L1, L2,L3
Module 4			
Interface Techniques: Introduction, signaling standard, chip-chip communication networks, ESD protection, Driver design techniques, receiver design techniques.			L1, L2,L3
Module 5			
Clocking styles: Introduction, clock jitter and skew, clock			L1, L2,L3

generation and clock distribution.

Course Outcomes: After studying this course, students will be able to:

1. Accomplish their goal in achieving the trade offs in performance, power, area, reliability and cost by the selection of design styles.
2. Analyse strengths and weakness of non-clocked static circuit families in terms of characteristics.
3. Differentiate the styles used for clocked and non-clocked circuit families.
4. Interpret the performance considerations to enable high speed communication; by choosing the input and output convention compatible with signal levels required for the design.

Question paper pattern:

- The question paper will have 10 full questions carrying equal marks.
- Each full question consists of 16 marks with a maximum of four sub questions.
- There will be 2 full questions from each module covering all the topics of the module
- The students will have to answer 5 full questions, selecting one full question from each module.

Text Book:

Kerry Bernstein & et. Al., "**High Speed CMOS Design Styles**", Kluwer, 1999.

Reference Books:

1. Howard Johnson & Martin Graham, "**High Speed Digital Design**" A Handbook of Black Magic, Prentice Hall PTR, 1993.
2. William S. Dally & John W. Poulton, "**Digital Systems Engineering**", Cambridge University Press, 1998.
3. Masakazu Shoji, "**High Speed Digital Circuits**", Addison Wesley Publishing Company, 1996.

Reconfigurable Computing			
[As per Choice Based credit System (CBCS) Scheme SEMESTER – IV			
Subject Code	16ELD424	IA Marks	20
Number of Lecture Hours/Week	03	Exam marks	80
Total Number of Lecture Hours	40 (8 Hours per Module)	Exam Hours	03
CREDITS – 03			
<p>Course Objectives: The aim of this course is to enable the students to</p> <ul style="list-style-type: none"> • Acquire fundamental knowledge and understanding of principles and practice in reconfigurable architecture. • Understand the FPGA design principles, and logic synthesis. • Integrate hardware and software technologies for reconfiguration computing focusing on partial reconfiguration design. • Focus on different domains of applications on reconfigurable computing. 			
Modules			RBT Level
Module 1			
<p>Introduction :History, Reconfigurable Vs Processor based system, RC Architecture. Reconfigurable Logic Devices: Field Programmable Gate Array, Coarse Grained Reconfigurable Arrays. Reconfigurable Computing System: Parallel Processing on Reconfigurable Computers, A survey of Reconfigurable Computing System. (Text 1)</p>			LI, L2
Module 2			
<p>Languages and Compilation: Design Cycle, Languages, HDL, High Level Compilation, Low level Design flow, Debugging Reconfigurable Computing Applications. (Text 1)</p>			L1,L2
Module 3			
<p>Implementation: Integration, FPGA Design flow, Logic Synthesis. High Level Synthesis for Reconfigurable Devices: Modelling, Temporal Partitioning Algorithms. (Text 2)</p>			L1, L2, L3
Module 4			
<p>Partial Reconfiguration Design: Partial Reconfiguration Design, Bitstream Manipulation with JBits, The modular Design flow, The Early Access Design Flow, Creating Partially Reconfigurable Designs, Partial Reconfiguration using Hansel-C Designs, Platform Design. (Text 2)</p>			L1,L2
Module 5			
<p>Signal Processing Applications: Reconfigurable computing for DSP, DSP application building blocks, Examples: Beamforming, Software Radio, Image and video processing, Local Neighbourhood functions, Convolution. (Text 1)</p> <p>System on a Programmable Chip: Introduction to SoPC, Adaptive Multiprocessing on Chip. (Text 2)</p>			L1, L2, L3
<p>Course Outcomes::After studying this course, students will be able to:</p> <ul style="list-style-type: none"> • Simulate and synthesize the reconfigurable computing architectures. • Use the reconfigurable architectures for the design of a digital system. 			

- Design of digital systems for a variety of applications on signal processing and system on chip configurations.

Question paper pattern:

- The question paper will have 10 full questions carrying equal marks.
- Each full question consists of 16 marks with a maximum of four sub questions.
- There will be 2 full questions from each module covering all the topics of the module
- The students will have to answer 5 full questions, selecting one full question from each module.

Text Books:

1. M. Gokhale and P. Graham, “Reconfigurable Computing: Accelerating Computation with Field-Programmable Gate Arrays”, Springer, 2005.
2. C. Bobda, “Introduction to Reconfigurable Computing: Architectures, Algorithms and Applications”, Springer, 2007.

Reference Books:

1. D. Pellerin and S. Thibault, “Practical FPGA Programming in C”, Prentice-Hall, 2005.
2. W. Wolf, “FPGA Based System Design”, Prentice-Hall, 2004.
3. R. Cofer and B. Harding, “Rapid System Prototyping with FPGAs: Accelerating the Design Process”, Newnes, 2005.